



**Höchstzulässige Werte / Maximum rated values**

**Elektrische Eigenschaften / Electrical properties**

Kollektor-Emitter-Sperrspannung collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{CES}$	1200	V
Kollektor-Dauergleichstrom DC-collector current	$T_C = 80^{\circ}\text{C}$	$I_{C,nom.}$	300	A
	$T_C = 25^{\circ}\text{C}$	$I_C$	625	A
Periodischer Kollektor Spitzenstrom repetitive peak collector current	$t_p = 1\text{ ms}, T_C = 80^{\circ}\text{C}$	$I_{CRM}$	600	A
Gesamt-Verlustleistung total power dissipation	$T_C = 25^{\circ}\text{C}, \text{ Transistor}$	$P_{tot}$	2,5	kW
Gate-Emitter-Spitzenspannung gate-emitter peak voltage		$V_{GES}$	+/- 20V	V
Dauergleichstrom DC forward current		$I_F$	300	A
Periodischer Spitzenstrom repetitive peak forw. current	$t_p = 1\text{ ms}$	$I_{FRM}$	600	A
Grenzlastintegral der Diode $I^2t$ - value, Diode	$V_R = 0\text{V}, t_p = 10\text{ms}, T_{vj} = 125^{\circ}\text{C}$	$I^2t$	19	$\text{k A}^2\text{s}$
Isolations-Prüfspannung insulation test voltage	RMS, $f = 50\text{ Hz}, t = 1\text{ min.}$	$V_{ISOL}$	2,5	kV

**Charakteristische Werte / Characteristic values**

**Transistor / Transistor**

min. typ. max.

Kollektor-Emitter Sättigungsspannung collector-emitter saturation voltage	$I_C = 300\text{A}, V_{GE} = 15\text{V}, T_{vj} = 25^{\circ}\text{C}$	$V_{CE\text{ sat}}$	-	2,1	2,6	V
	$I_C = 300\text{A}, V_{GE} = 15\text{V}, T_{vj} = 125^{\circ}\text{C}$		-	2,4	2,9	V
Gate-Schwellenspannung gate threshold voltage	$I_C = 12\text{mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$	$V_{GE(th)}$	4,5	5,5	6,5	V
Gateladung gate charge	$V_{GE} = -15\text{V} \dots +15\text{V}$	$Q_G$	-	3,2	-	$\mu\text{C}$
Eingangskapazität input capacitance	$f = 1\text{MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$	$C_{ies}$	-	21	-	nF
Rückwirkungskapazität reverse transfer capacitance	$f = 1\text{MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$	$C_{res}$	-	1,4	-	nF
Kollektor-Emitter Reststrom collector-emitter cut-off current	$V_{GE} = 0\text{V}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 1200\text{V}$	$I_{CES}$	-	-	5	mA
Gate-Emitter Reststrom gate-emitter leakage current	$V_{CE} = 0\text{V}, V_{GE} = 20\text{V}, T_{vj} = 25^{\circ}\text{C}$	$I_{GES}$	-	-	400	nA

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**Charakteristische Werte / Characteristic values**

Transistor / Transistor		min.	typ.	max.		
Einschaltverzögerungszeit (ind. Last) turn on delay time (inductive load)	$I_C = 300A, V_{CE} = 600V$ $V_{GE} = \pm 15V, R_G = 3,3\Omega, T_{vj} = 25^\circ C$	$t_{d,on}$	-	0,05	-	$\mu s$
	$V_{GE} = \pm 15V, R_G = 3,3\Omega, T_{vj} = 125^\circ C$		-	0,06	-	$\mu s$
Anstiegszeit (induktive Last) rise time (inductive load)	$I_C = 300A, V_{CE} = 600V$ $V_{GE} = \pm 15V, R_G = 3,3\Omega, T_{vj} = 25^\circ C$	$t_r$	-	0,05	-	$\mu s$
	$V_{GE} = \pm 15V, R_G = 3,3\Omega, T_{vj} = 125^\circ C$		-	0,07	-	$\mu s$
Abschaltverzögerungszeit (ind. Last) turn off delay time (inductive load)	$I_C = 300A, V_{CE} = 600V$ $V_{GE} = \pm 15V, R_G = 3,3\Omega, T_{vj} = 25^\circ C$	$t_{d,off}$	-	0,57	-	$\mu s$
	$V_{GE} = \pm 15V, R_G = 3,3\Omega, T_{vj} = 125^\circ C$		-	0,57	-	$\mu s$
Fallzeit (induktive Last) fall time (inductive load)	$I_C = 300A, V_{CE} = 600V$ $V_{GE} = \pm 15V, R_G = 3,3\Omega, T_{vj} = 25^\circ C$	$t_f$	-	0,04	-	$\mu s$
	$V_{GE} = \pm 15V, R_G = 3,3\Omega, T_{vj} = 125^\circ C$		-	0,05	-	$\mu s$
Einschaltverlustenergie pro Puls turn-on energy loss per pulse	$I_C = 300A, V_{CE} = 600V, V_{GE} = \pm 15V$ $R_G = 3,3\Omega, T_{vj} = 125^\circ C, L_\sigma = 60nH$	$E_{on}$	-	35	-	mJ
Abschaltverlustenergie pro Puls turn-off energy loss per pulse	$I_C = 300A, V_{CE} = 600V, V_{GE} = \pm 15V$ $R_G = 3,3\Omega, T_{vj} = 125^\circ C, L_\sigma = 60nH$	$E_{off}$	-	36	-	mJ
Kurzschlußverhalten SC Data	$t_F \leq 10\mu s, V_{GE} \leq 15V, R_G = 3,3\Omega$ $T_{vj} \leq 125^\circ C, V_{CC} = 900V, V_{CEmax} = V_{CES} - L_{\sigma CE} \cdot di/dt$	$I_{SC}$	-	1800	-	A
Modulinduktivität stray inductance module	Anschlüsse / terminals 2-3	$L_{\sigma CE}$	-	25	-	nH
Modul Leitungswiderstand, Anschlüsse – Chip module lead resistance, terminals – chip	pro Zweig / per arm, $T_C = 25^\circ C$	$R_{CC+EE}$	-	0,60	-	m $\Omega$

**Charakteristische Werte / Characteristic values**

Diode / Diode		min.	typ.	max.		
Durchlaßspannung forward voltage	$I_F = 300A, V_{GE} = 0V, T_{vj} = 25^\circ C$	$V_F$	-	1,8	2,3	V
	$I_F = 300A, V_{GE} = 0V, T_{vj} = 125^\circ C$		-	1,7	2,2	V
Rückstromspitze peak reverse recovery current	$I_F = 300A, -di_F/dt = 5400A/\mu s$ $V_R = 600V, V_{GE} = -15V, T_{vj} = 25^\circ C$	$I_{RM}$	-	348	-	A
	$V_R = 600V, V_{GE} = -15V, T_{vj} = 125^\circ C$		-	420	-	A
Sperrverzögerungsladung recovered charge	$I_F = 300A, -di_F/dt = 5400A/\mu s$ $V_R = 600V, V_{GE} = -15V, T_{vj} = 25^\circ C$	$Q_r$	-	28	-	$\mu C$
	$V_R = 600V, V_{GE} = -15V, T_{vj} = 125^\circ C$		-	58	-	$\mu C$
Abschaltenergie pro Puls reverse recovery energy	$I_F = 300A, -di_F/dt = 5400A/\mu s$ $V_R = 600V, V_{GE} = -15V, T_{vj} = 25^\circ C$	$E_{rec}$	-	9	-	mJ
	$V_R = 600V, V_{GE} = -15V, T_{vj} = 125^\circ C$		-	21	-	mJ



**Thermische Eigenschaften / Thermal properties**

			min.	typ.	max.	
Innerer Wärmewiderstand thermal resistance, junction to case	pro Transistor / per transistor, DC	$R_{thJC}$	-	-	0,050	K/W
	pro Diode / per Diode, DC		-	-	0,125	K/W
Übergangs-Wärmewiderstand thermal resistance, case to heatsink	pro Modul / per module $\lambda_{Paste} = 1 \text{ W/m} \cdot \text{K}$ / $\lambda_{grease} = 1 \text{ W/m} \cdot \text{K}$	$R_{thCK}$	-	0,010	-	K/W
Höchstzulässige Sperschichttemperatur maximum junction temperature		$T_{vj \text{ max}}$	-	-	150	°C
Betriebstemperatur operation temperature		$T_{vj \text{ op}}$	-40	-	125	°C
Lagertemperatur storage temperature		$T_{stg}$	-40	-	125	°C

**Mechanische Eigenschaften / Mechanical properties**

Gehäuse, siehe Anlage case, see appendix						
Innere Isolation internal insulation				$\text{Al}_2\text{O}_3$		
Kriechstrecke creepage distance				20		mm
Luftstrecke clearance distance				11		mm
CTI comperative tracking index				225		
Anzugsdrehmoment f. mech. Befestigung mounting torque	Schraube / screw M6	M	3,0	-	6,0	Nm
Anzugsdrehmoment f. elektr. Anschlüsse terminal connection torque	Anschlüsse / terminals M6	M	2,5	-	5,0	Nm
Gewicht weight		G		340		g

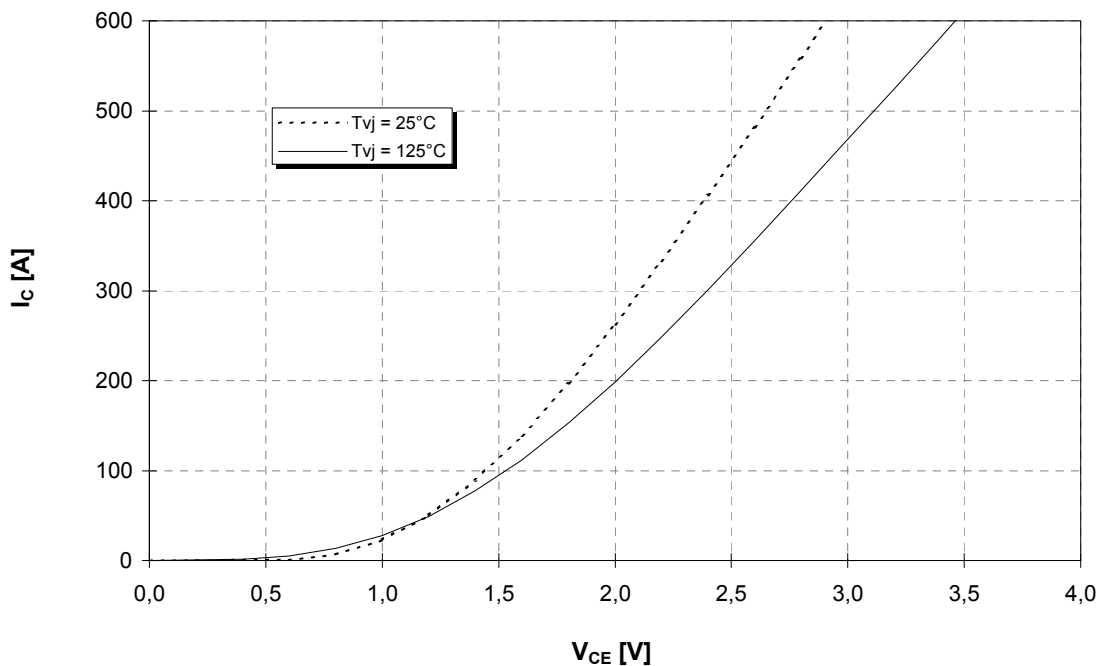
Mit dieser technischen Information werden Halbleiterbauelemente spezifiziert, jedoch keine Eigenschaften zugesichert. Sie gilt in Verbindung mit den zugehörigen Technischen Erläuterungen.

This technical information specifies semiconductor devices but promises no characteristics. It is valid in combination with the belonging technical notes.



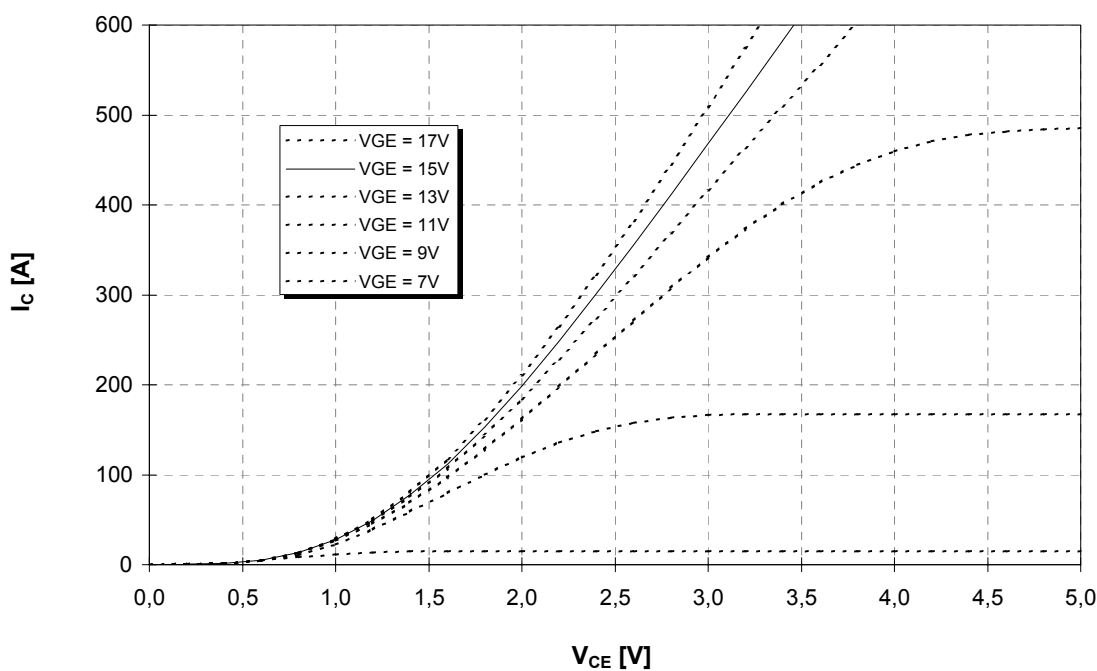
**Ausgangskennlinie (typisch)**  
**Output characteristic (typical)**

$I_C = f(V_{CE})$   
 $V_{GE} = 15V$



**Ausgangskennlinienfeld (typisch)**  
**Output characteristic (typical)**

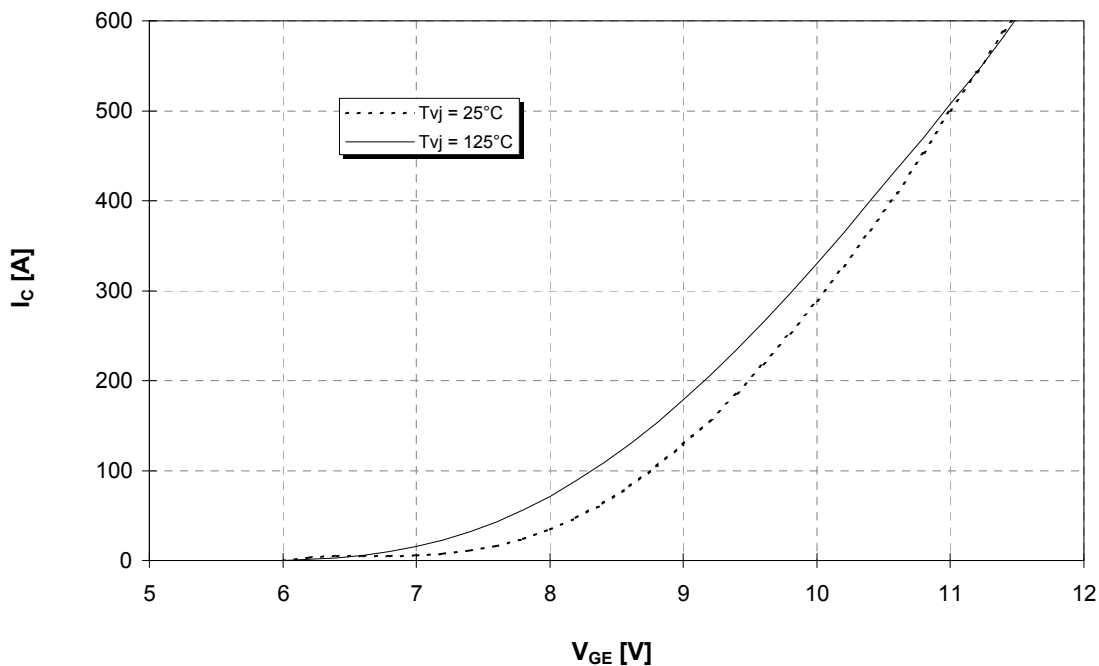
$I_C = f(V_{CE})$   
 $T_{vj} = 125^\circ C$





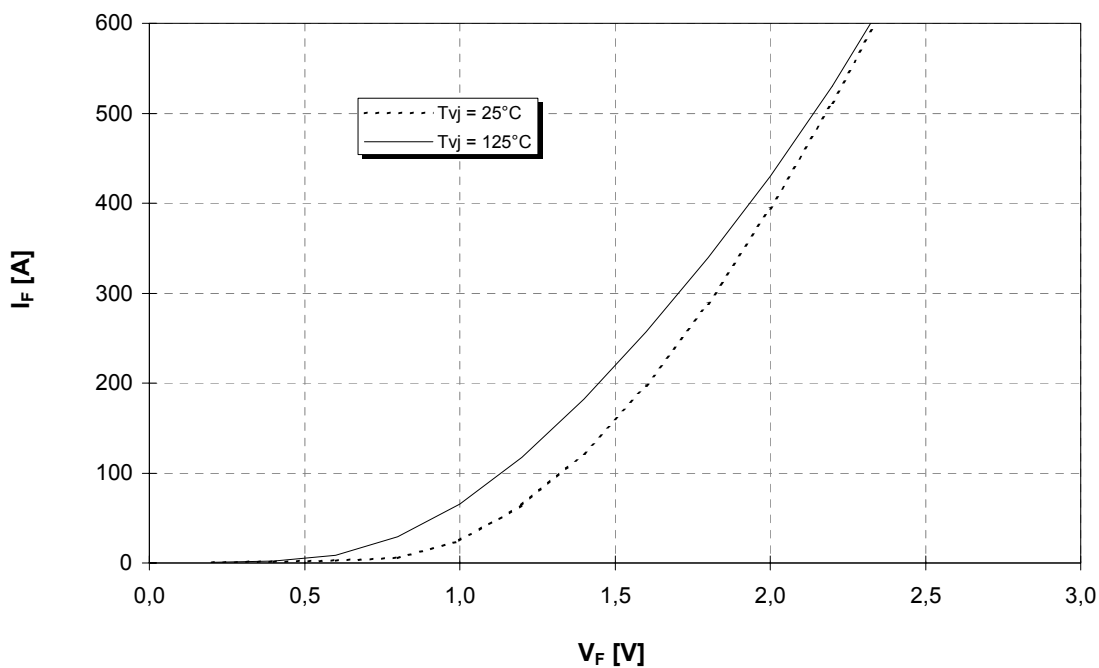
Übertragungscharakteristik (typisch)  
Transfer characteristic (typical)

$I_C = f(V_{GE})$   
 $V_{CE} = 20V$



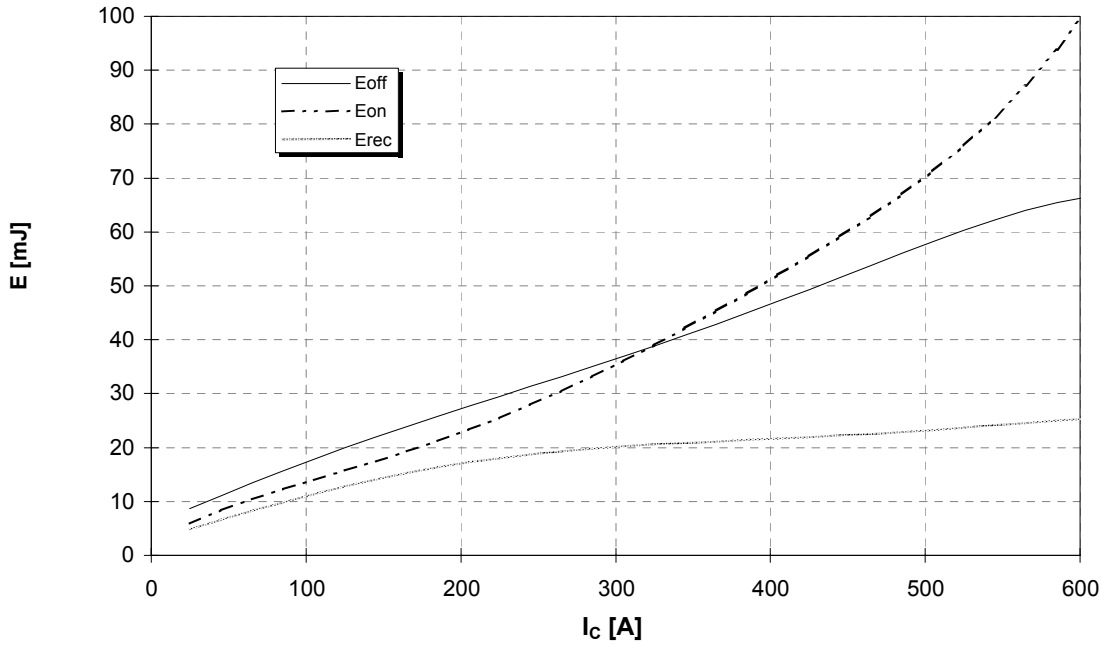
Durchlaßkennlinie der Inversdiode (typisch)  
Forward characteristic of inverse diode (typical)

$I_F = f(V_F)$

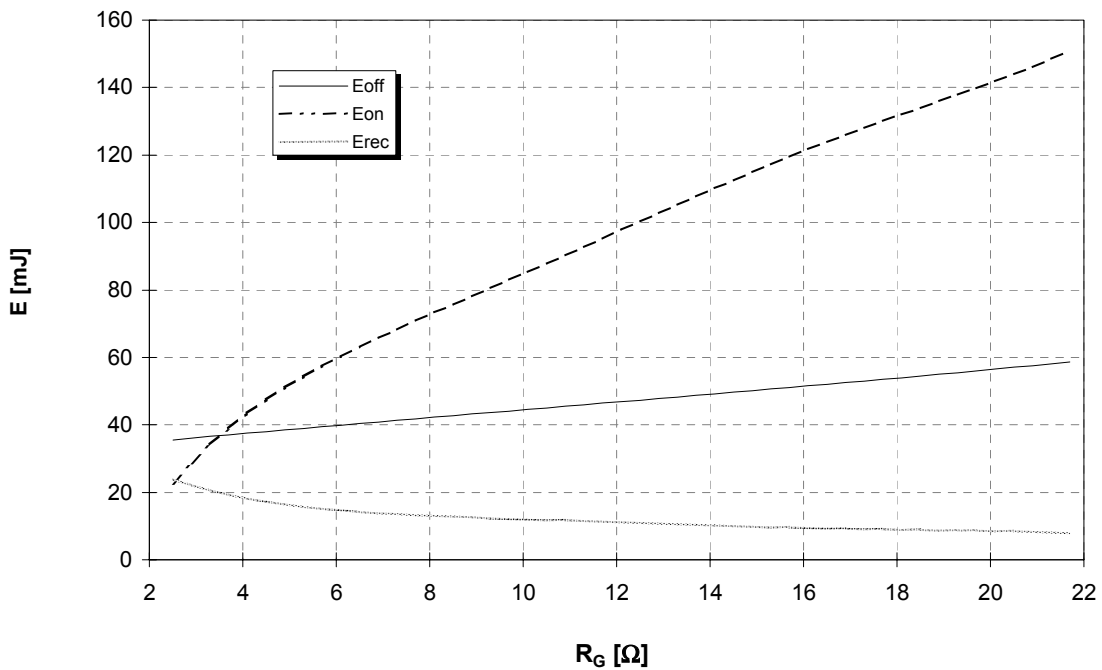




**Schaltverluste (typisch)  $E_{on} = f(I_C)$ ,  $E_{off} = f(I_C)$ ,  $E_{rec} = f(I_C)$**   
**Switching losses (typical)  $V_{GE} = \pm 15V$ ,  $R_G = 3,3 \Omega$ ,  $V_{CE} = 600V$ ,  $T_{vj} = 125^\circ C$**

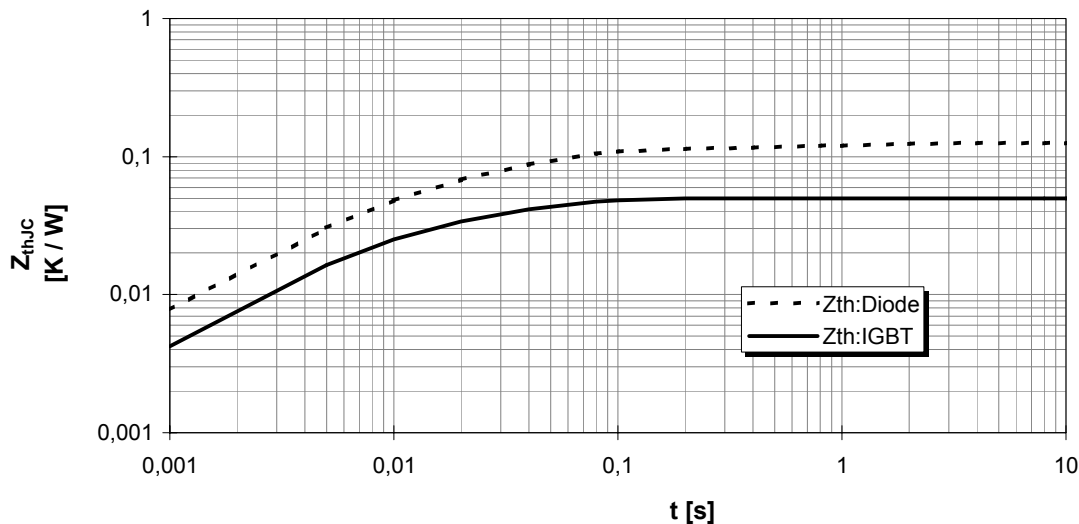


**Schaltverluste (typisch)  $E_{on} = f(R_G)$ ,  $E_{off} = f(R_G)$ ,  $E_{rec} = f(R_G)$**   
**Switching losses (typical)  $V_{GE} = \pm 15V$ ,  $I_C = 300A$ ,  $V_{CE} = 600V$ ,  $T_{vj} = 125^\circ C$**



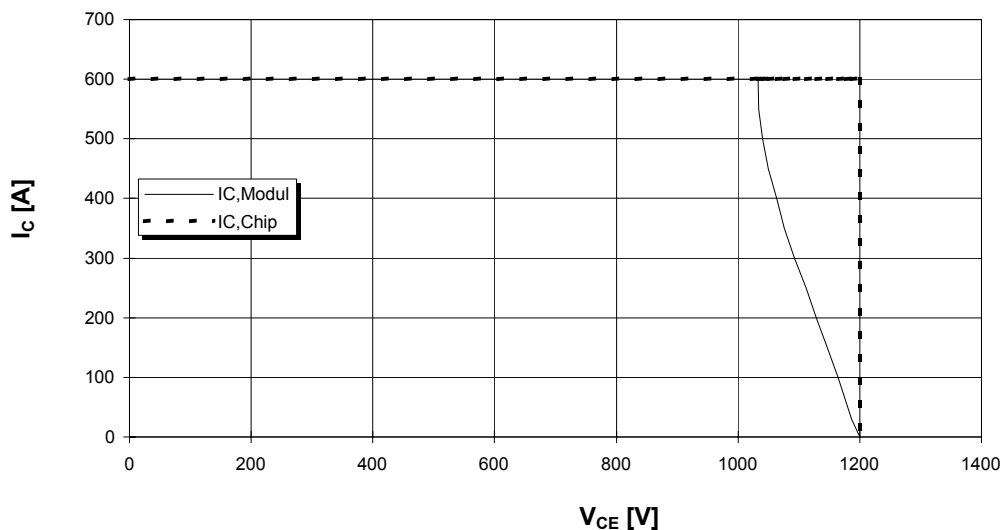


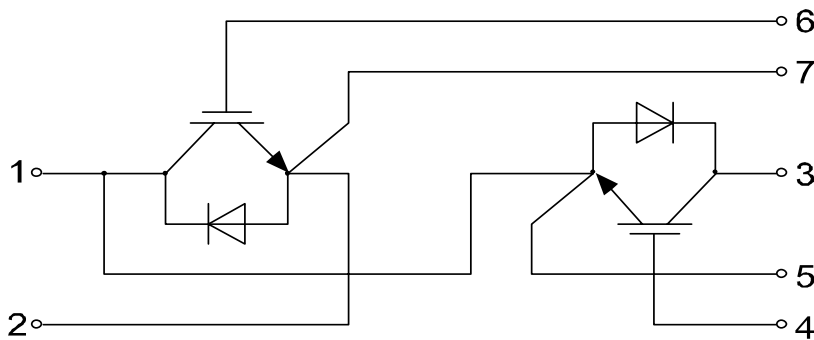
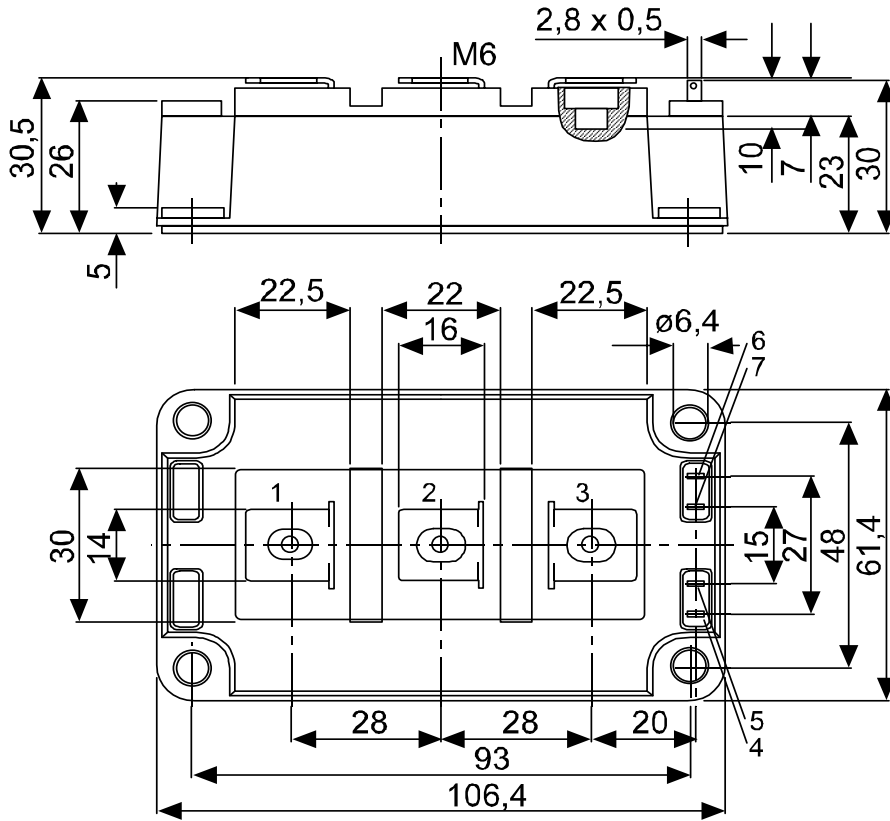
**Transienter Wärmewiderstand**  $Z_{thJC} = f(t)$   
**Transient thermal impedance**



i	1	2	3	4
$r_i$ [K/kW] : IGBT	21,02	25,19	2,85	0,94
$\tau_i$ [s] : IGBT	6,499E-02	2,601E-02	2,364E-03	1,187E-05
$r_i$ [K/kW] : Diode	52,55	62,97	7,13	2,35
$\tau_i$ [s] : Diode	6,499E-02	2,601E-02	2,364E-03	1,187E-05

**Sicherer Arbeitsbereich (RBSOA)**  
**Reverse bias safe operation area (RBSOA)**  $V_{GE} = \pm 15V, R_G = 3,3 \Omega, T_{vj} = 125^\circ C$









**Anhang C-Serie**  
**Appendix C-series**

**Gehäuse spezifische Werte**  
**Housing specific values**

		typ.		
CTI comperative tracking index			425	
Modulinduktivität stray inductance module	terminals 2-3	$L_{\sigma CE}$	20	nH
Modul Leitungswiderstand, Anschlüsse – Chip module lead resistance, terminals – chip	pro Zweig/per arm $T_c=25^\circ C$	$R_{CC+EE}$	0,6	m $\Omega$

**Gehäusemaße C-Serie**  
**Package outline C-series**

